

# Multilayer Power Inductor

## CIG32W Series (3225/ EIA 1210)



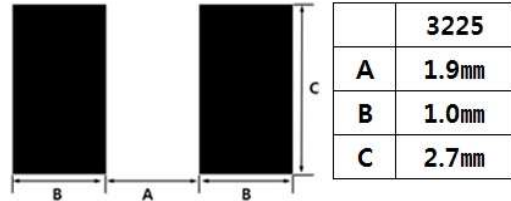
### APPLICATION

Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

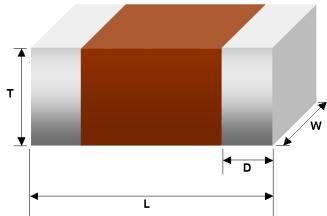
### FEATURES

- High Current Type
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability

### RECOMMENDED LAND PATTERN



### DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
32	3.2±0.2	2.5±0.2	0.9±0.1	0.5±0.3

### DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) <sup>*1</sup> Typ.	Rated Current (A) <sup>*2</sup>	
					Max.	Typ.
CIG32W1R0MNE	1210/3225	1.0±20%	0.06±25 %	2.7	1.5	2.0

※Rated Current (A)<sup>\*1</sup>: DC current value when Inductance drops to 30% of nominal Inductance value (ONLY REFERENCE)

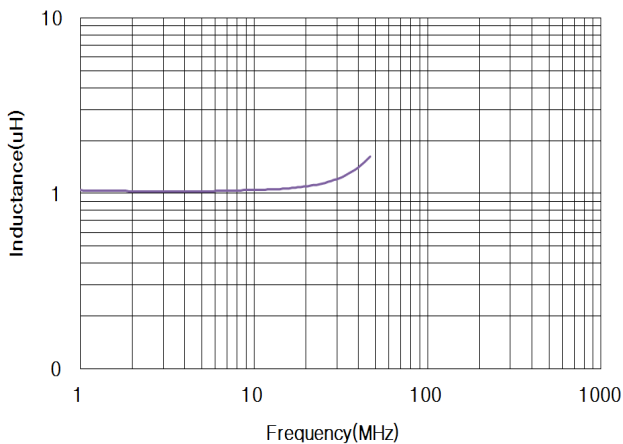
※Rated Current (A)<sup>\*2</sup>: DC current value when the self-generation of heat rises to 40°C (Reference ambient temperature:25°C)

※Operating temperature range: -40 to +125°C (Including self-temperature rise)

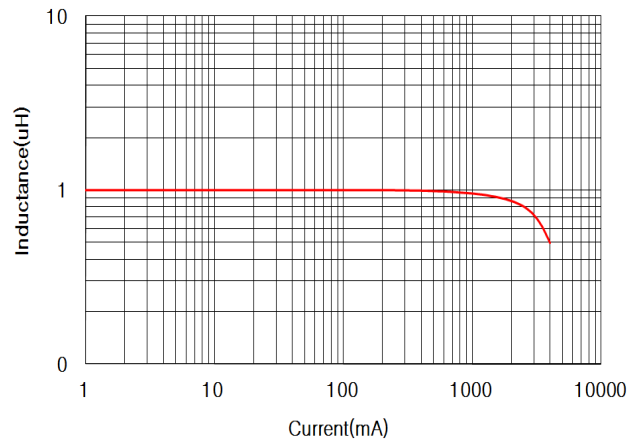
※Test equipment: Agilent :E4991A+16092A

### CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



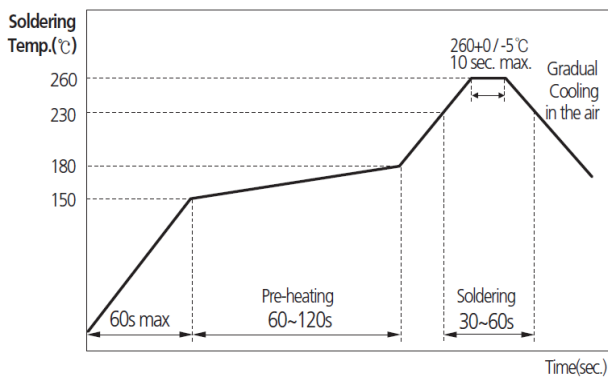
**PRODUCT IDENTIFICATION**

**CI G 32 W 1R0 M N E**  
**(1) (2) (3) (4) (5) (6) (7) (8)**

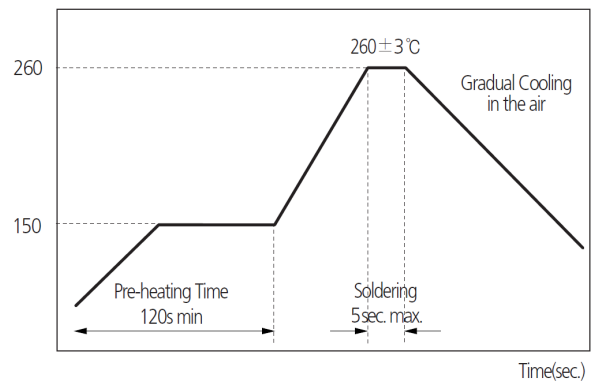
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (W:Normal Type)
- (5) Inductance (1R0:1.0uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

**RECOMMENDED SOLDERING CONDITION**

**REFLOW SOLDERING**



**FLOW SOLDERING**



**PACKAGING**

Packaging Style	Quantity(pcs/reel)
Embossed Taping	2,500

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.